TOSHIBA Multi-Chip Transistor Silicon NPN & PNP Epitaxial Type

TPC6901

High-Speed Switching Applications MOS Gate Drive Applications

- NPN and PNP transistors are mounted on a compact and slim package.
- High DC current gain: NPN $h_{FE} = 400$ to 1000 : PNP $h_{FE} = 200$ to 500
- Low collector-emitter saturation voltage
 : NPN V_{CE} (sat) = 0.17 V (max)
 : PNP V_{CE} (sat) = 0.23 V (max)
- High-speed switching: NPN tf = 85 ns (typ.)
 : PNP tf = 70 ns (typ.)



Weight: 0.011 g (typ.)

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		a	Rating			
		Symbol	NPN	PNP	Unit	
Collector-base voltage		V _{CBO}	100	-50	V	
Collector-emitter voltage		V _{CEX}	80	-50	V	
Collector-emitter voltage		V _{CEO}	50	-50	V	
Emitter-base voltage		V _{EBO}	7	-7	V	
Collector current	DC (Note 1)	Ι _C	1.0	0.7	А	
	Pulse (Note 1)	I _{CP}	2.0	-2.0	А	
Base current		Ι _Β	0.1	-0.1	А	
Collector power dissipation (t=10 s) (Note 2)	Single-device operation	P _C (1)	500		mW	
Collector power dissipation (DC) (Note 2)	Single-device operation	P _C (2)	400			
	Single-device value at dual operation	P _C (3)	330		mW	
Thermal resistance, junction to ambient (t=10 s) (Note 2)	Single-device operation	R _{th (j-a)} (1)	250		°C/W	
Thermal resistance, junction to ambient (DC) (Note 2)	Single-device operation	R _{th (j-a)} (2)	312		°C/W	
	Single-device value at dual operation	R _{th (j-a)} (3)	378			
Junction temperature		Тj	150		°C	
Storage temperature range		T _{stg}	–55 to 150		°C	

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: Mounted on an FR4 board (glass epoxy, 1.6 mm thick, Cu area: 645 mm²)

Note 3: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Circuit Configuration







Electrical Characteristics (Ta = 25°C) : NPN

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off current		I _{CBO}	$V_{CB} = 100 \text{ V}, \text{ I}_{E} = 0$			100	nA
Emitter cut-off current		I _{EBO}	$V_{EB}=7~V,~I_C=0$	_	_	100	nA
Collector-emitter breakdown voltage		V (BR) CEO	$I_C = 10 \text{ mA}, I_B = 0$	50	_	—	V
DC current gain		h _{FE} (1)	$V_{CE} = 2 V, I_C = 0.1 A$	400	_	1000	
		h _{FE} (2)	$V_{CE} = 2 V, I_C = 0.3 A$	200	_	_	
Collector-emitter saturation voltage		V _{CE (sat)}	$I_{C} = 300 \text{ mA}, I_{B} = 6 \text{ mA}$	_	_	0.17	V
Base-emitter saturation voltage		V _{BE (sat)}	$I_{C} = 300 \text{ mA}, I_{B} = 6 \text{ mA}$	_	_	1.10	V
Collector output capacitance		C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$	_	5	_	pF
Switching time	Rise time	tr	See Figure 1 circuit diagram.		35		
	Storage time	t _{stg}	V _{CC} ≈ 30 V, R _L = 100 Ω		680		ns
	Fall time	t _f	$I_{B1} = -I_{B2} = 10 \text{ mA}$		85		

Electrical Characteristics (Ta = 25°C) : PNP

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Collector cut-off current		I _{CBO}	$V_{CB} = -50 \text{ V}, \text{ I}_{E} = 0$			-100	nA
Emitter cut-off current		I _{EBO}	$V_{EB} = -7 \text{ V}, \text{ I}_{C} = 0$			-100	nA
Collector-emitter breakdown voltage		V (BR) CEO	$I_{C} = -10 \text{ mA}, I_{B} = 0$	-50		_	V
DC current gain		h _{FE} (1)	$V_{CE} = -2 \text{ V}, \text{ I}_{C} = -0.1 \text{ A}$	200		500	
		h _{FE} (2)	$V_{CE} = -2 \text{ V}, \text{ I}_{C} = -0.3 \text{ A}$	125	_	_	
Collector-emitter saturation voltage		V _{CE (sat)}	$I_{C} = -300 \text{ mA}, I_{B} = -10 \text{ mA}$			0.23	V
Base-emitter saturation voltage		V _{BE (sat)}	$I_{C} = -300 \text{ mA}, I_{B} = -10 \text{ mA}$	_	_	1.10	V
Collector output capacitance		C _{ob}	$V_{CB} = -10 \text{ V}, \text{ I}_{E} = 0, \text{ f} = 1 \text{ MHz}$		8	_	pF
Switching time	Rise time	t _r	See Figure 2 circuit diagram.		60		
	Storage time	t _{stg}	V _{CC} ≈ 30 V, R _L = 100 Ω		280	—	ns
	Fall time	t _f	$I_{B1} = -I_{B2} = -10 \text{ mA}$		70		







Figure 2 Switching Time Test Circuit & Timing Chart (PNP)

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NPN











Safe Operation Area



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PNP











Safe operation area



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Common



Permissible Power Dissipation for Simultaneous Operation 0.5 DC operation Permissible power dissipation for Q2 $$P_{\rm C}$$ (W) Ta = 25°C Mounted on an FR4 board glass epoxy 0.4 I.6 mm thick, Cu area: 645 mm²) 0.3 0.2 0.1 0L 0.1 0.3 0.2 0.4 0.5 Permissible power dissipation for Q1 Pc (W) Collector power dissipation at the single-device

operation is 0.4W. Collector power dissipation at the single-device value at dual operation is 0.33W.

Collector power dissipation at the dual operation is set to 0.66W.

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